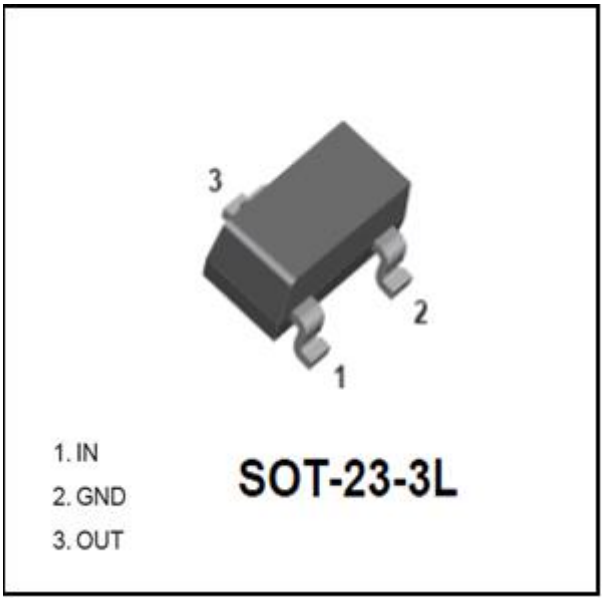
Digital Transistors (Built-in Resistors)



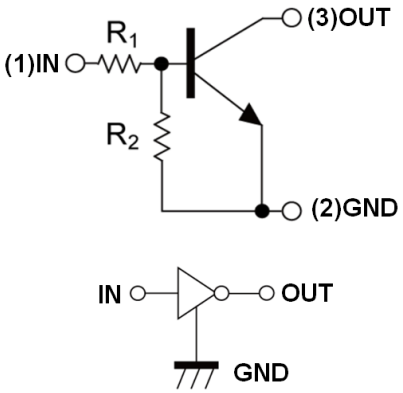
Features

●Epoxy meets UL-94 V-0 flammability rating
●Moisture Sensitivity Level 1
●Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors
●Surface mount package ideally Suited for Automatic Insertion
●NPN

Mechanical Data

● **Package**: SOT-23-3L
● **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
● **Marking:** 24

■Equivalent circuit



■Maximum Ratings (Ta=25℃ Unless otherwise specified)

ITEM	SYMBOL	UNIT	CONDITIONS	VALUE
Supply Voltage	V_{CC}	V		50
Input Voltage	V_{IN}	V		-10 to +40
Output Current	I_O	mA		100
Power Dissipation	P_D	mW		200
Junction Temperature	T_J	℃		-55 to +150
Storage Temperature	T_{STG}	℃		-55 to +150

■Electrical Characteristics (Ta=25℃ unless otherwise specified)

ITEM	SYMBOL	UNIT	CONDITIONS	MIN	TYP	MAX
Input voltage	$VI_{(off)}$	V	V_{CC}=5V,Ic=100uA	0.5		
	$VI_{(on)}$	V	V_0=0.3V,Ic=10mA			3
Output voltage	$Vo_{(on)}$	V	Io /Ii =10mA/0.5 mA			0.3
Input current	II	mA	V_I=5V			0.88
Output current	$I_{O(off)}$	uA	V_{CC}=50V, Vi=0			0.5
DC current gain	GI		Vo=5V, Io =5mA	30		
Input resistance	R_1	kΩ		7	10	13
Resistance ratio	R_2/R_1			0.8	1	1.2
Transition frequency	fT	MHz	Vo=10V,I_O=5mA,f=100MHz		250	

■ Thermal Characteristics

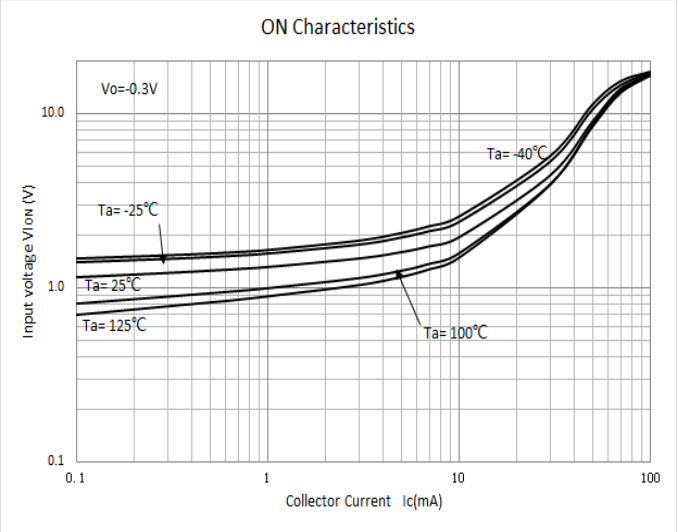
Parameter	Symbol	Unit	Value
Thermal resistance, junction-to-ambient	$R\theta J\text{-}A^{(1)}$	℃/W	625
Thermal resistance, junction-to-case	$R\theta J\text{-}C^{(1)}$	℃/W	500

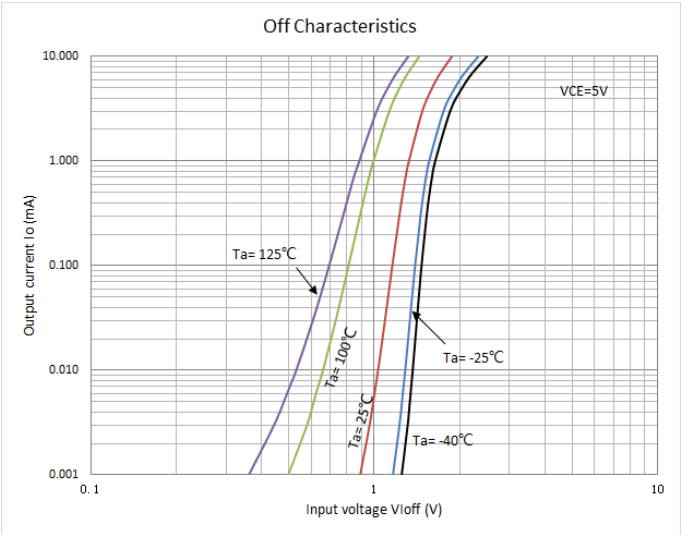
Note:
（1）Device mounted on PCB，single-sided copper，with standard footprint.

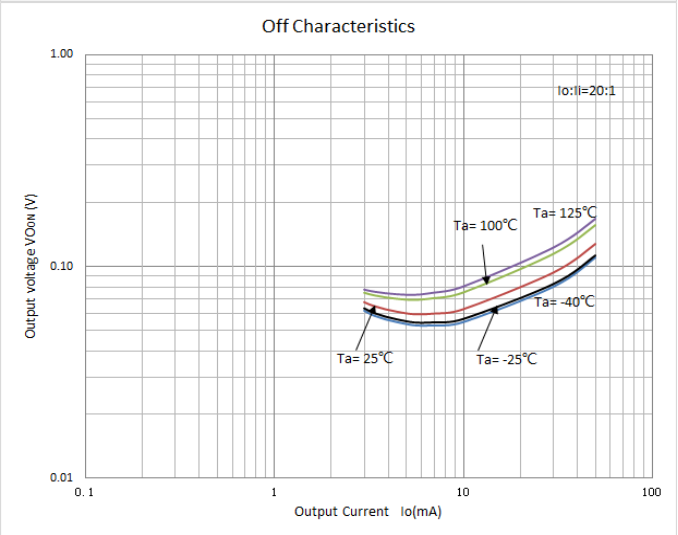
■ Ordering Information (Example)

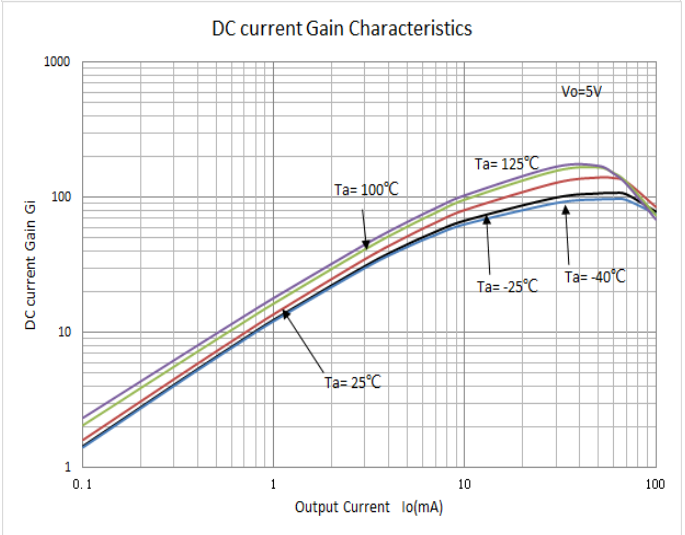
PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
DTC114EKA	F2	Approximate 0.014	3000	30000	120000	7” reel

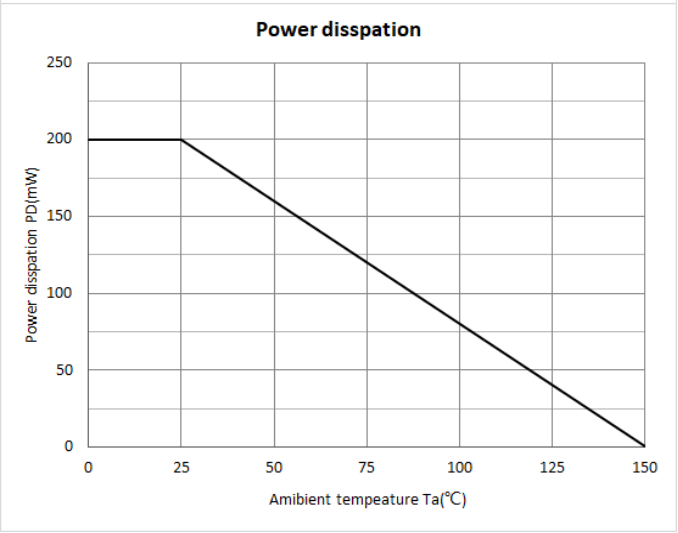
■ **Characteristics** (Typical)



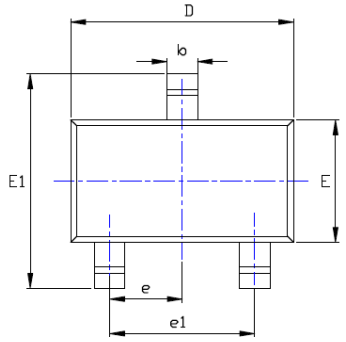




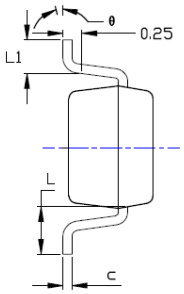




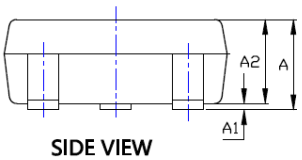
■SOT-23-3L Package Outline Dimensions



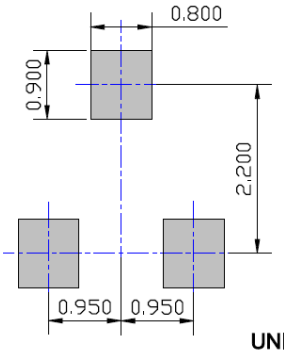
TOP VIEW



SIDE VIEW



SIDE VIEW



UNIT：mm

DIMENSIONS				
SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.041	0.049	1.050	1.250
A1	0.000	0.008	0.000	0.200
A2	0.041	0.045	1.050	1.150
b	0.012	0.020	0.300	0.500
c	0.004	0.008	0.100	0.200
D	0.111	0.119	2.820	3.020
E	0.059	0.067	1.500	1.700
E1	0.104	0.116	2.650	2.950
e	0.037TYP		0.950TYP	
e1	0.071	0.079	1.800	2.000
L	0.024REF		0.600REF	
L1	0.012	0.024	0.300	0.600
ø	0°	8°	0°	8°

NOTE:
1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

SUGGESTED SOLDER PAD LAYOUT

Note:
1. All dimensions are in millimeters (mm) unless otherwise specified.
[所有尺寸均以毫米为单位，除非另有说明]
2. General tolerances: ±0.10mm unless otherwise specified.
[通用公差为±0.10mm，除非另有说明]
3. Dimensions and tolerances per ASME Y14.5M-2018.
[尺寸和公差遵循 ASME Y14.5M-2018 标准]
4.All dimensions shown are exclusive of burrs and gate residues. Burrs and gate vestiges shall not exceed 0.15 mm in maximum.
[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]
5.Dimension b does not include dambar protrusion of max 0.100 mm per side.
[尺寸b不包括单边最大0.100 MM的中筋凸出部分]
6.Dimensions D and E are the overall extreme outer dimensions of the mold compound. These dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.
[D和E是塑封体的外部极限尺寸，不包括包封溢料、内引线溢料、凸出部分以及胶体毛刺，但是包含了包封错位的最大尺寸]
7.Formed leads shall be planar with respect to one another within a maximum of 0.076 mm relative to the seating plane.
[成型的管脚应为同一平面，共面性最大为0.1mm]
8. ★It is the key size.
[★ 标记为关键尺寸]

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